Amendments to Claims

Claims 1-10 (canceled)

a1

Claim 11 (currently amended): A process for bonding at least a first substrate to at least a second substrate, wherein at least a portion of at least one of said substrates has applied thereon [the adhesive of claim 1] a reactivatable adhesive composition comprising an effective amount of an energy-absorbing ingredient such that upon exposure of the adhesive to radiant energy having a wavelength of from about 400nm to about 100,000nm the adhesive is activated, said [method] process comprising [irradiating] exposing the applied adhesive with radiant energy having a wavelength of from about 400nm to about 100,000nm for a time sufficient to melt the adhesive, bringing one of said substrates in contact with the melted adhesive on the other substrate, and allowing the adhesive to solidify thereby bonding the first substrate to the second substrate.

Claim 12 (currently amended): A method of closing a container having applied on at least one surface substrate thereof [the] a reactivatable adhesive [of claim 1] composition comprising an effective amount of an energy-absorbing ingredient such that upon exposure of the adhesive to radiant energy having a wavelength of from about 400nm to about 100,000nm, the adhesive is activated, said method comprising exposing the reactivatable adhesive [of claim 1] to radiant energy having a wavelength of from about 400nm to about 100,000nm for a time sufficient to melt said adhesive, bringing a second surface substrate in contact with the reactivated adhesive on the first surface substrate and, optionally, applying pressure to effect said closing.

Claim 13 (original): The method of claim 12 wherein pressure is applied for less than about 30 seconds.

Claim 14 (original): The method of claim 12 where the adhesive is exposed to said radiant energy for less that about 5 seconds.

Claims 15-19 (canceled)

Claim 20 (new): The process of claim 11 wherein the adhesive is activated upon exposure to radiant energy having a wavelength of from about 750nm to about 5000nm.

Claim 21 (new): The process of claim 11 wherein the reactivatable adhesive is a hot melt adhesive.

Claim 22 (new): The process of claim 11 claim 1 wherein the energy-absorbing ingredient is dissolved in the adhesive composition.

Claim 23 (new): The process of claim 11 wherein the energy-absorbing ingredient is dispersed in the adhesive composition.

Claim 24 (new): The process of claim 22 wherein the energy-absorbing ingredient comprises an organic dye.

Claim 25 (new): The process of claim 23 wherein the energy-absorbing ingredient comprises a pigment.

Claim 26 (new): The process of claim 25 wherein the pigment is carbon black.

Claim 27 (new): The process of claim 26 wherein said effective amount of carbon black in said adhesive composition is greater than about 0.1 weight percent.

Claim 28 (new): The process of claim 25 wherein the pigment is graphite.

Claim 29 (new): The process of claim 11 wherein at least one of said substrates is paperboard or chipboard.

Claim 30 (new): The method of claim 12 wherein the adhesive is activated upon exposure to radiant energy having a wavelength of from about 750nm to about 5000nm.

Claim 31 (new): The method of claim 12 wherein the reactivatable adhesive is a hot melt adhesive.

Claim 32 (new): The method of claim 12 wherein the energy-absorbing ingredient is dissolved in the adhesive composition.

Claim 33 (new): The method of claim 12 wherein the energy-absorbing ingredient is dispersed in the adhesive composition.

Claim 34 (new): The method of claim 32 wherein the energy-absorbing ingredient comprises an organic dye.

a1

Claim 35 (new): The method of claim 33 wherein the energy-absorbing ingredient comprises a pigment.

Claim 36 (new): The method of claim 35 wherein the pigment is carbon black.

Claim 37 (new): The method of claim 36 wherein said effective amount of carbon black in said adhesive composition is greater than about 0.1 weight percent.

Claim 38 (new): The method of claim 35 wherein the pigment is graphite.

Claim 39 (new): The method of claim 12 wherein at least one of said substrates is paperboard or chipboard.